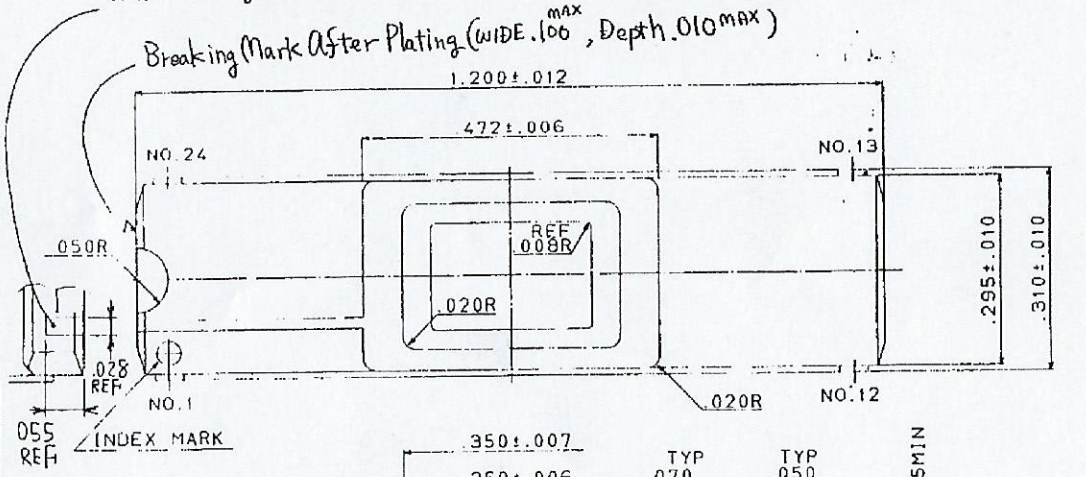
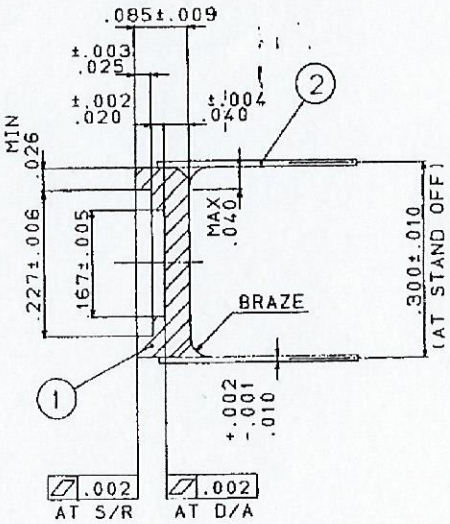
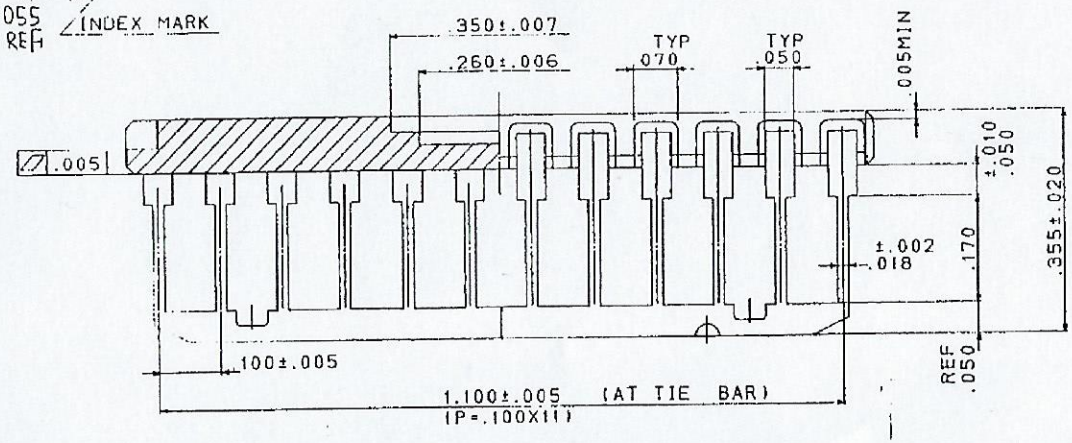
NTK TECHNICAL CERAMICS

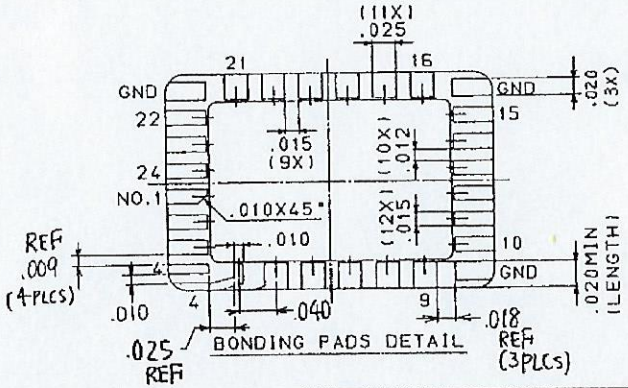
This Metallization to be connected To S/R, D/A & Gnd Pads.

Breaking Mark After Plating (WIDE .100 MAX, Depth .010 MAX)









NOTES:
1. GOLD PLATE 60μ INCHES MIN OVER 80μ INCHES MIN NICKEL.
2. GND PAD TO BE ELECTRICALLY CONNECTED TO THE SEAL RING AND DIE ATTACH.
3. LEAD RESISTANCE: 200mΩ MAX.

発行 02.10.11 技術部

Item	Name	Material	Description
2	LEAD	ALLOY42	
1	CERAMIC	BLACK ALUMINA	

UNLESS OTHERWISE SPECIFIED TOLERANCES: ± 1%
N. L. T. 2 DECIMALS .XX ±.01
3 DECIMALS .XXX ±.005

Rev.	Description	Date
Φ	NEW DRAWING	MAR-1 -1989

DRAWN HIRAMATSU
CHECKED K.Fujikawa
APPROVED J.W
UNIT INCH
SCALE 5/1

NTK TECHNICAL CERAMICS
NGK SPARK PLUG CO., LTD

TITLE: 24 LEAD S/B PACKAGE

DWG NO. IDK24F1-6332A

SIZE A-3